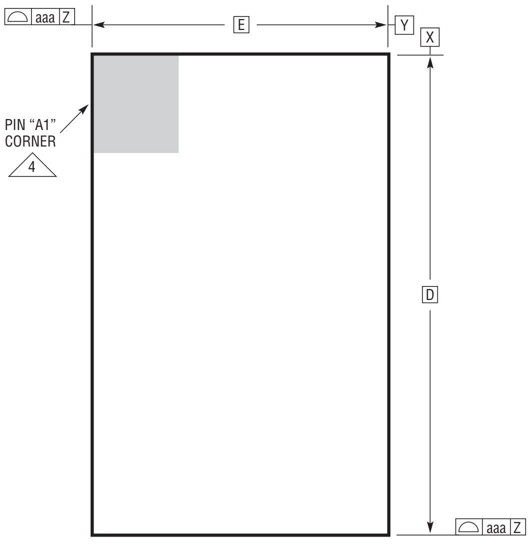
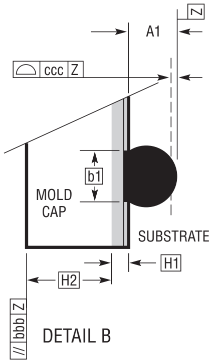
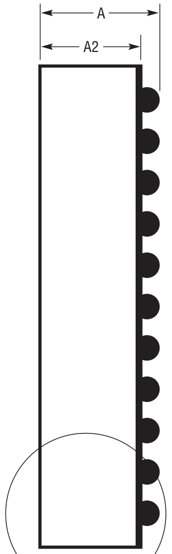
BGA Package
77-Lead (6.25mm × 4.00mm × 0.97mm)
(Reference LTC DWG# 05-08-1596 Rev Ø)



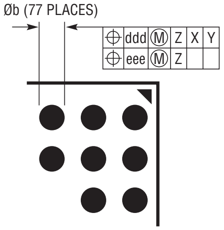
PACKAGE TOP VIEW



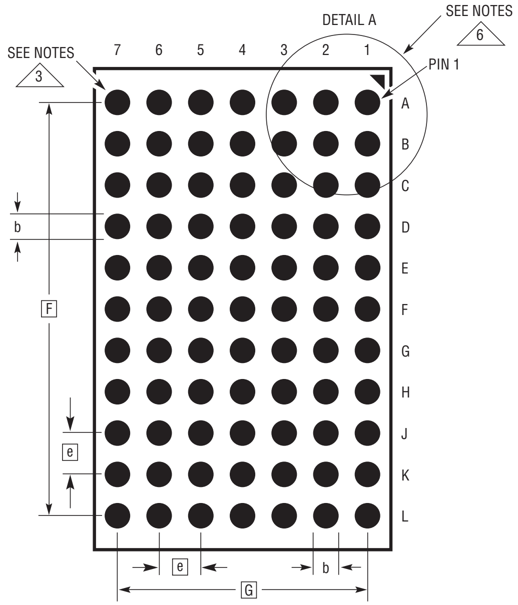
DETAIL B



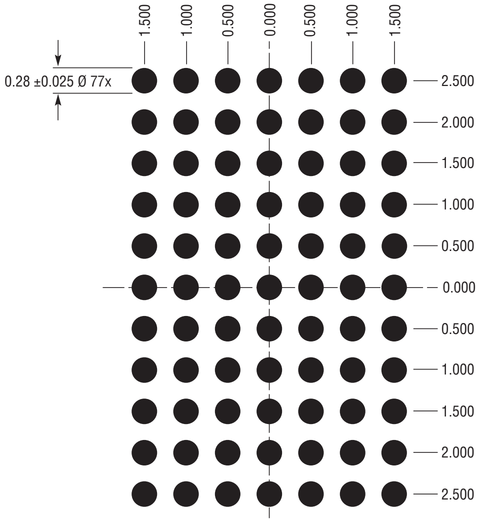
DETAIL B
PACKAGE SIDE VIEW



DETAIL A



PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	0.81	0.97	1.13	
A1	0.16	0.23	0.30	BALL HT
A2	0.65	0.74	0.83	
b	0.25	0.30	0.35	BALL DIMENSION
b1	0.25	0.28	0.31	PAD DIMENSION
D		6.25		
E		4.00		
e		0.50		
F		5.00		
G		3.00		
H1		0.24		SUBSTRATE THK
H2		0.50		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.08	
ddd			0.15	
eee			0.05	
TOTAL NUMBER OF BALLS: 77				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

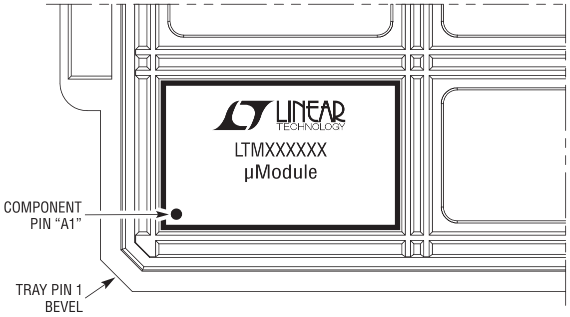
2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL,
BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR
MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY
AMONG μModule PRODUCTS. REVIEW EACH PACKAGE
LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION